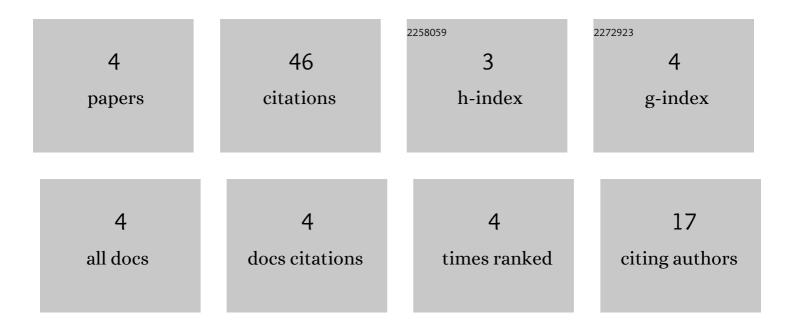


List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/6505398/publications.pdf Version: 2024-02-01



Клі 7нц

#	Article	IF	CITATIONS
1	Enhancing adhesion performance of sputtering Ti/Cu film on pretreated composite prepreg for stacking structure of IC substrates. Composites Part B: Engineering, 2019, 158, 400-405.	12.0	27
2	Convection-Dependent Competitive Adsorption between SPS and EO/PO on Copper Surface for Accelerating Trench Filling. Journal of the Electrochemical Society, 2019, 166, D93-D98.	2.9	14
3	Communication—Localized Accelerator Pre-Adsorption to Speed Up Copper Electroplating Microvia Filling. Journal of the Electrochemical Society, 2019, 166, D467-D469.	2.9	3
4	Anisotropic growth of electroless nickel‑phosphorus plating on fine sliver lines for L-shape terminal electrode structure of chip inductor. Applied Surface Science, 2019, 496, 143633.	6.1	2